

Amendments to the Claims:

The listing of claims will replace all prior versions and listings of claims in the application:

5 Listing of Claims:

1.(currently amended) A scribe line structure, comprising:

10 a substrate;

15 a plurality of dielectric layers formed on the surface of the substrate comprising at least a process monitor pattern set in a cutting area, wherein the cutting area is contacted with a cutting apparatus for separating individual dies; and

20 a dummy metal structure formed on the surface of the substrate connecting with the process monitor pattern and exposed in the cutting area.

25 2.(original) The scribe line structure of claim 1 wherein the plurality of dielectric layers comprise dielectric layers having a dielectric constant less than or equal to 3.

30 3.(original) The scribe line structure of claim 1 wherein the dummy metal structure comprises a plurality of dummy vias.

35 4.(original) The scribe line structure of claim 1 wherein the dummy metal structure comprises a plurality of dummy metal layers.

40 5.(original) The scribe line structure of claim 1 wherein the process monitor pattern is made of metal materials.

6.(original) The scribe line structure of claim 1 wherein the process monitor pattern comprises test keys, feature dimension measuring elements, or alignment marks.

5 7.(previously presented) The scribe line structure of claim 1 wherein the surface of the substrate further comprises a protective layer covering two sides of the surface of dielectric within the cutting area.

8.(currently amended) A scribe line structure, comprising:

10 a substrate, the surface of the substrate comprising at least a cutting area to be contacted with a cutting apparatus for separating individual dies;

a plurality of dielectric layers formed on the surface of the substrate comprising at least a process monitor pattern set in the cutting area; and

15 a heat irradiative structure formed in the plurality of dielectric layers connecting the plurality of dielectric layers with the surface of the substrate and exposed in the cutting area.

20 9.(original) The scribe line structure of claim 8 wherein the plurality of dielectric layers comprise dielectric layers having a dielectric constant less than or equal to 3.

25 10.(original) The scribe line structure of claim 8 wherein the heat irradiative structure is a dummy metal structure.

11.(original) The scribe line structure of claim 10 wherein the dummy metal structure comprises a plurality of dummy vias.

12.(original) The scribe line structure of claim 10 wherein the dummy metal structure comprises a plurality of dummy metal layers.

5 13.(original) The scribe line structure of claim 8 wherein the heat irradiative structure connects with the process monitor pattern.

14.(original) The scribe line structure of claim 8 wherein the process monitor pattern is made of metal materials.

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15.(original) The scribe line structure of claim 8 wherein the process monitor pattern comprises test keys, feature dimension measuring elements, or alignment marks.

15 16.(previously presented) The scribe line structure of claim 8 wherein the surface of the substrate further comprises a protective layer covering two sides of the surface of dielectric within the cutting area.

20 17.(previously presented) The scribe line structure of claim 1, wherein the process monitor pattern is set under the cutting area.

18.(currently amended) The scribe line structure of claim 8, wherein the process monitor pattern is set under the cutting area.

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